

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A device comprising:

a first layer of a multilayer substrate having a first portion and a second portion;
a second layer of a multilayer substrate having a third portion and a fourth portion;
a first section of an inductor disposed in the second portion of the first layer;
a second section of the inductor disposed in the third portion of the second layer,
the second section of the inductor coupled at a plurality of locations to the first section of
the inductor;
a shielding plane disposed between the first layer and the second layer;
a first dielectric layer disposed between the first layer of a multilayer substrate and
the shielding plane; and
a second dielectric layer disposed between the first layer of a multilayer substrate
and the shielding plane,
wherein an imaginary vector normal to the first section of an inductor does not
intersect any other section of the inductor.

2. (Original) A device according to Claim 1, wherein the shielding plane comprises a
ground plane.

3. (Original) A device according to Claim 1, wherein current is to flow in a first direction in the first portion of the inductor and in a second direction opposite to the first direction in the second portion of the inductor.

4. (Withdrawn) A device according to Claim 1, further comprising:

a third portion of the inductor disposed in a third layer of the multilayer substrate, the third portion coupled to the second portion; and

a second shielding plane disposed between the second portion and the third portion.

5. (Original) A device according to Claim 1, wherein the inductor comprises a spiral turn inductor.

6. (Previously Presented) A device according to Claim 1, further comprising:

a plurality of vias to couple the first portion to the second portion.

7. (Previously Presented) A device according to Claim 1, further comprising:

a plurality of pin-through holes to couple the first portion to the second portion.

8. (Original) A device according to Claim 1, further comprising:

a dielectric disposed between the first layer and the shielding plane and between the second layer and the shielding plane.

9. (Currently Amended) A method comprising:

fabricating a first layer of a multilayer substrate having a first portion and a second portion;

fabricating a second layer of a multilayer substrate having a third portion and a fourth portion;

fabricating a first section of an inductor disposed in the second portion of the first layer;

fabricating a second section of the inductor disposed in the third portion of the second layer, the second section of the inductor coupled at a plurality of locations to the first section of the inductor;

fabricating a shielding plane disposed between the first layer and the second layer;

fabricating a first dielectric layer disposed between the first layer of a multilayer substrate and the shielding plane; and

fabricating a second dielectric layer disposed between the first layer of a multilayer substrate and the shielding plane,

wherein an imaginary vector normal to the first section of an inductor does not intersect any other section of the inductor.

10. (Original) A method according to Claim 9, wherein the shielding plane comprises a ground plane.

11. (Original) A method according to Claim 9, wherein current is to flow in a first direction in the first portion of the inductor and in a second direction opposite to the first direction in the second portion of the inductor.

12. (Withdrawn) A method according to Claim 9, further comprising:

 fabricating a fourth layer of the multilayer substrate above the third layer, the fourth layer comprising a second shielding plane; and

 fabricating a fifth layer of the multilayer substrate above the fourth layer, the fifth layer comprising a third portion of the inductor,

 wherein the fourth layer comprises a second coupling to electrically couple the second portion of the inductor to the third portion of the inductor.

13. (Withdrawn) A system comprising:

 an integrated circuit package comprising:

 a first portion of an inductor disposed in a first layer of the integrated circuit package;

 a second portion of the inductor disposed in a second layer of the integrated circuit package, the second portion coupled to the first portion; and

 a shielding plane disposed between the first portion and the second portion; and

 a double data rate memory in communication with the integrated circuit package.

14. (Withdrawn) A system according to Claim 13, further comprising:

 an integrated circuit die coupled to the integrated circuit package, the integrated circuit package to transmit data between the integrated circuit die and the memory.

15. (Withdrawn) A system according to Claim 13, wherein the shielding plane comprises a ground plane.

16. (Withdrawn) A system according to Claim 13, wherein current is to flow in a first direction in the first portion of the inductor and in a second direction opposite to the first direction in the second portion of the inductor.

17. (Withdrawn) A system according to Claim 13, further comprising:
a third portion of the inductor disposed in a third layer of the multilayer substrate, the third portion coupled to the second portion; and
a second shielding plane disposed between the second portion and the third portion.